

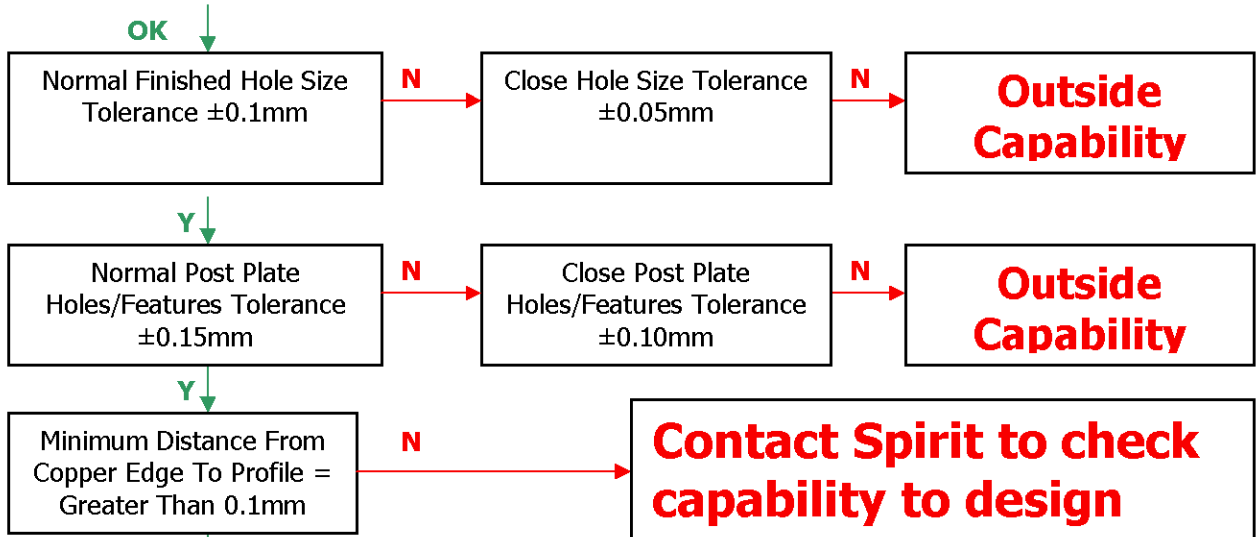
Base Copper	Minimum Conductor Widths & Spacings	Other then stated opposite
18µm	0.10mm	Contact Spirit to check capability to design
35µm	0.15mm	
70µm	0.20mm	
If Base Copper Is Higher Than 70µm →		

OK ↓ Continue On Page 2

CAPABILITY CHECKLIST – For External Distribution

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Material Thickness	Minimum Drill Size (8:1)	Other then stated opposite
Up To 1.6mm	0.20mm	Contact Spirit to check capability to design
1.61mm To 2.4mm	0.30mm	
2.41mm To 3.2mm	0.40mm	
Material Thicker Than 3.2mm →		



Base Copper	Minimum Annular Ring On Pads	Other then stated opposite
18µm	0.10mm	Contact Spirit to check capability to design
35µm	0.15mm	
70µm	0.20mm	

OK ↓

Standard Rigid Material	Other Rigid Materials Available	Standard Multilayer Material	Other Multi Layer Materials Available	If Not Listed
Standard And High TG FR4	BT Epoxy - FR2 Cem1 - Cem3 Ceramics - PTFE	Standard And High TG FR4 Copper Foils – 1080 Prepreg – 2113 Prepreg - 7628 Prepreg	BT Epoxy	Contact Spirit to check capability to design

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<p style="text-align: center;">Surface Finishes</p> <p style="text-align: center;">Tin Lead Hot Air Level – Electroless Silver Lead Free Hot Air Level (On Circuit 1.6mm Thick, Or Less) – Electroless Nickel & Immersion Gold Gold On Copper (Hard Gold) - Bare Copper – Carbon Ink – Immersion Tin – OSP</p>	<p style="color: red; font-weight: bold;">N</p> <p style="color: red; font-weight: bold;">Contact Spirit to check capability to design</p>
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<p style="text-align: center;">Non-Standard Operations</p> <p style="text-align: center;">Laser Cutting - Plugged Via Holes - Half Hole Plating Skip Scoring – Serialization - Bar Coding – Milling</p>	<p style="color: red; font-weight: bold;">Y</p> <p style="color: red; font-weight: bold;">Contact Spirit to check capability to design</p>
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N

Solder Mask				
Colour	Type	Minimum Solder Mask Dam	Minimum Annular Clearance To Copper	Other then stated opposite
Green	Photoimageable	0.075mm	0.05mm	Contact Spirit to check capability to design
Soldermask Thickness Is 15µm ±5µm – Any Different Requirements				

OK

Peelable Mask				
Colour	Minimum Feature	Minimum Clearance To Hole	Maximum Tented Hole	If Outside
Green	0.50mm	0.50mm	3.0mm	Contact Spirit to check capability to design
Blue	0.50mm	0.50mm	3.0mm	

OK

Ident / Legend / Notation					
Colour	Minimum Feature	Minimum Clearance	UV Cureable	Two Pack	Other
White	0.15mm	0.15mm	X	X	Contact Spirit to check capability to design
Yellow	0.15mm	0.15mm	X	X	

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Scoring Information	
Tolerance Of Score Line To Circuit Pattern	±0.25mm
Tolerance Of Score Line to Score Line	±0.15mm
Minimum Gap Between Copper Edge And Centre Of Score Line	±0.50mm
Web Thickness Of Score Unless Stated	0.4mm ±0.1mm

OK



Chamfer Information	
Standard Chamfer is Between 30° and 45 ° On 1 Edge	Other requirement contact Spirit
Minimum Distance Between Copper And Chamfered Edge	$(([Material\ Thickness]/3) * \tan[Angle]) + 0.1mm$

OK



Workmanship & Releases/Approvals	
Release	Comments
UL	Specific design features to be verified by Spirit
Workmanship Standard Is To IPC-1-600 Class 1, 2 or 3 – Default Class = 2	